MGBR10L40 Preliminary DIODE

TO-277

QW-R601-202.a

MOS GATED BARRIER RECTIFIER

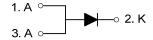
■ DESCRIPTION

The UTC MGBR10L40 is a surface mount mos gatedbarrier rectifier, it uses UTC's advanced technology to provide customers withlow forward voltage drop and high switching speed, etc.

■ FEATURES

- * Low forward voltage drop
- * High switching speed

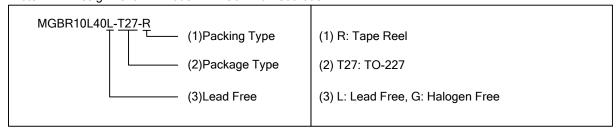
■ SYMBOL



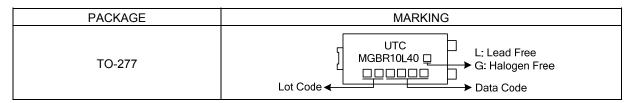
■ ORDERING INFORMATION

Ordering Number		Daalaasa	Pin Assignment			Dankina	
Lead Free	Halogen Free	Package	1	2	3	Packing	
MGBR10L40L-T27-R	MGBR10L40G-T27-R	TO-277	Α	K	Α	Tape Reel	

Note: Pin Assignment: A: Anode K: Common Cathode



MARKING INFORMATION



www.unisonic.com.tw 1 of 3

■ **ABSOLUTE MAXIMUM RATINGS**(T_A=25°C, unless otherwise specified)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

PARAMETER	SYMBOL	RATINGS	UNIT
DC Blocking Voltage	V_{RM}	40	٧
WorkingPeak Reverse Voltage	V_{RWM}	40	٧
Peak Repetitive Reverse Voltage	V_{RRM}	40	٧
Average Rectified Output Current T _C =140°C	Ιο	10	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	150	Α
Repetitive Peak Avalanche Power (1µs, 25°C)	P _{ARM}	5000	W
Operating Junction Temperature	TJ	-65~+150	Ŝ
Storage Temperature	T _{STG}	-65~+150	°C

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

■ THERMAL CHARACTERISTICS (Note 3)

PARAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient	θ_{JA}	73	°C/W	
Junction to Case	θ _{JC}	13	°C/W	

■ ELECTRICAL CHARACTERISTICS(T_A=25°C,unless otherwise specified.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Reverse Breakdown Voltage (Note 1)	$V_{(BR)R}$	I _R =0.5mA	40			V
Forward Voltage Drop	V _{FM}	I _F =10A, T _J =25°C			0.57	V
		I _F =10A, T _J =125°C			0.52	V
Leakage Current (Note 1)	I _{RM}	V _R =40V, T _J =25°C		80	300	μΑ
		V _R =40V, T _J =125°C		12	40	mA

Notes: 1. Short duration pulse test used to minimize self-heating effect.

- 2. Thermal resistance junction to case mounted on heatsink.
- 3. Mounted on an FR4 PCB, single-sided copper, with 100 cm² copper pad area.

UTC assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all UTC products described or contained herein. UTC products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice.

